

MA2Z720

Silicon epitaxial planar type

For high frequency rectification

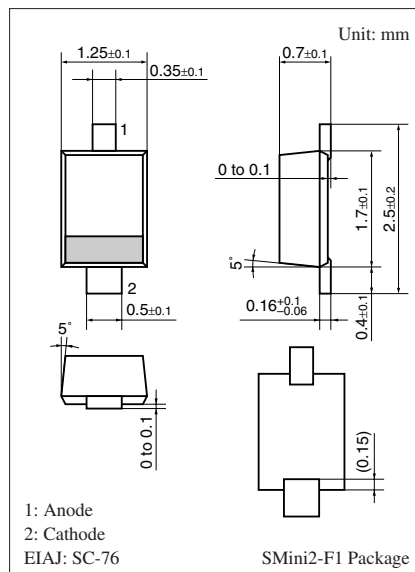
■ Features

- Forward current (Average) $I_{F(AV)} = 500$ mA rectification is possible
- High-density mounting is possible

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---|-------------|-------------|------------------|
| Reverse voltage | V_R | 40 | V |
| Maximum peak reverse voltage | V_{RM} | 40 | V |
| Forward current (Average) | $I_{F(AV)}$ | 500 | mA |
| Non-repetitive peak forward surge current * | I_{FSM} | 2 | A |
| Junction temperature | T_j | 125 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +125 | $^\circ\text{C}$ |

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: 2L

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

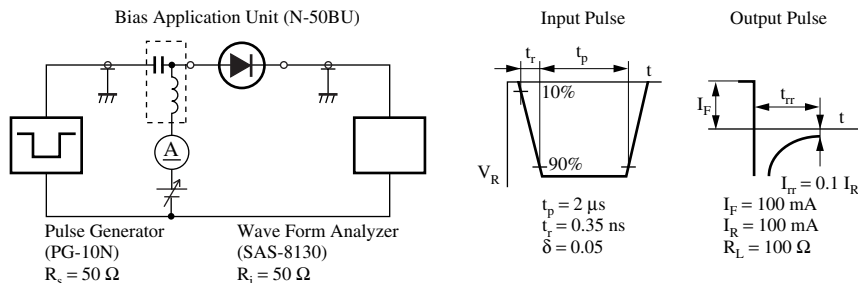
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-------------------------|----------|---|-----|-----|------|---------------|
| Forward voltage | V_F | $I_F = 500$ mA | | | 0.55 | V |
| Reverse current | I_R | $V_R = 35$ V | | | 100 | μA |
| Terminal capacitance | C_t | $V_R = 0$ V, $f = 1$ MHz | | 60 | | pF |
| Reverse recovery time * | t_{rr} | $I_F = I_R = 100$ mA $I_{Tr} = 0.1 I_R$, $R_L = 100 \Omega$ | | 5 | | ns |

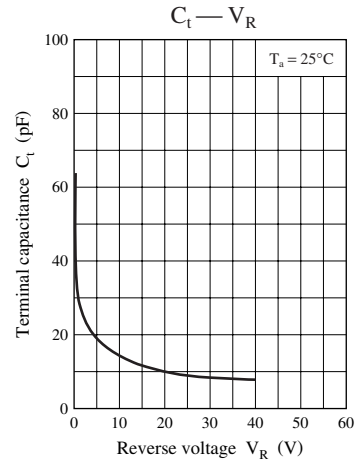
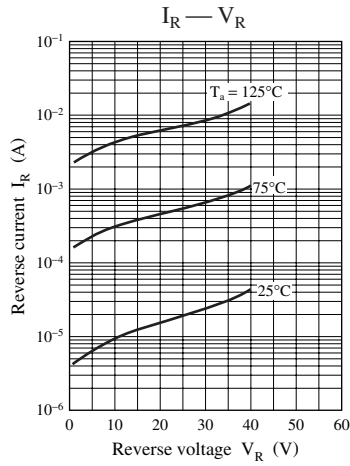
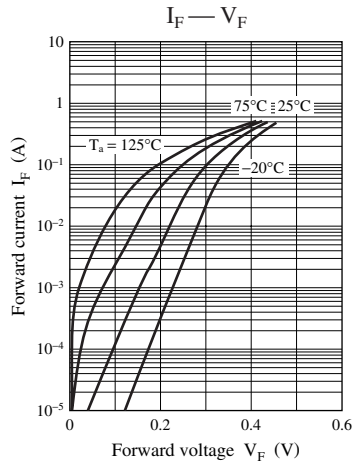
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 400 MHz.

4.*: t_{rr} measurement circuit





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